

Abstract of the Disclosure

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The present invention provides a semiconductor package in which a semiconductor chip, a die pad, an adhesive, metal wires, LOC type inner leads and standard type inner leads are sealed with a sealing resin. The LOC type inner leads and the standard type inner leads are arranged on a same plane and mixedly arranged along a side of the semiconductor chip. Clearance between the inner leads and the die pad is set to be larger than a sum of thickness of the semiconductor chip and the bonding material. Thus, a semiconductor chip having electrode pads broadly distributed and arranged thereon can be employed and the modulus of section of the semiconductor package can be enhanced.